

## SnBi35Ag0.3 4-5LT95

No Clean Solder Paste



### Product Description

Asahi SnBi35Ag0.3 4-5LT95 medium-temperature solder alloy was developed to have better wettability in reflow soldering process. The flux residue is clear, colourless, and provide excellent electrical resistivity.

SnBi35Ag0.3 4-5LT95 solder paste exhibits long stencil life and tack time, while still delivering exceptional solderability. It possesses excellent printing characteristics to a wide variety of metallization with an anti-slump property.

### Application

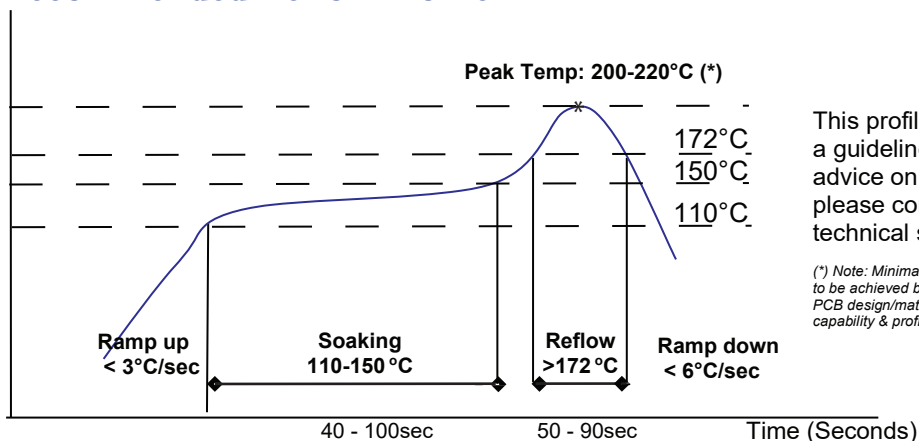
SnBi35Ag0.3 4-5LT95 is designed for standard stencil printing. The printing speed can be set at 25 - 100 mm/sec. Its optimum printing condition is 23 to 25 °C and humidity of 50 to 65 %RH, with at least 24 hours stencil life of continuous printing (process dependant).

### Specification (Preliminary)

Item	Result
<b>Alloy</b>	
Alloy Composition	Sn/Bi35/Ag0.3
Melting Temperature	151~172 °C
Differential Scanning Calorimetry	
Powder Size	20 – 38 μm, Type IV,
IPC TM-650 2.2.14	Mesh Size -400 / +635
<b>Paste Flux</b>	
Flux Content	12.0 +/- 1.0 wt%
IPC-TM-650 2.2.20	
Halide Content	Not detected
JIS Z 3197 8.1.4.2.1	
Water Extract Resistivity	> 1 x 10 <sup>5</sup> Ω-cm
JIS Z 3197 8.1.1	
Copper Mirror Test	Classified as “L”, Pass
IPC-TM-650 2.3.32	
Flux Activity Classification	ROLO
IPC J-STD-004	
<b>Solder Paste</b>	
Viscosity	400 - 1000 kcPs
IPC-TM-650 2.4.34	
JIS Z 3284 Annex 6	80 - 220 Pa.s
Tackiness	> 100gf
JIS Z 3284 Annex 9	
Surface Insulation Resistance	> 1 x 10 <sup>8</sup> Ω, Pass
(85°C, 85%RH, 168hrs)	
IPC-TM-650 2.6.3.3	
Electromigration	Pass
(85°C, 88.5%RH, 596hrs)	
IPC-TM-650 2.6.14.1	
Slump Test	Pass
JIS Z 3284 Annex 7, Annex 8	
Solder Ball Test	Pass
IPC-TM-650 2.4.43	
JIS Z 3284 Annex 11	

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## Recommended Reflow Profile



This profile is simply a guideline. For more advice on profiling, please contact Asahi technical support.

(\*) Note: Minimal peak temperature to be achieved but is dependent on PCB design/material and process capability & profiling in accuracy.

## Residue Removal

Residue removal is not needed as this is a no clean solder paste. For assemblies that require cleaning, call Asahi technical support.

## Storage, Handling and Shelf Life

Solder paste has to be thawed to room temperature (~25°C) prior using to avoid condensation. Paste left on the stencil should not be put back into the container together with the unused paste. It is preferable not to re-use solder paste left on the stencil after printing.

Generally the solder paste could last for 3 months from date of manufacturing, if kept under proper condition and temperature of 0 - 10 °C.

## Health and Safety

Do not handle the paste with your bare hand. Use proper tool when handling the paste. If the paste touches the skin, wash thoroughly with soap and water. For more information, please refer to Material Safety Data Sheet.

## Packaging

Packaging Type	Weight	Packaging Part
Jar	500g	E
	250g	F
Cartridge	1000g	D
Cassette	800g	I
Easipak	150g	J
	50g	H

## Solder Paste Product Order System:

Alloy Type      Powder Size      -      Formula Type      -      Packaging Part

Example:      SnBi35Ag0.3 4-5LT95-E

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